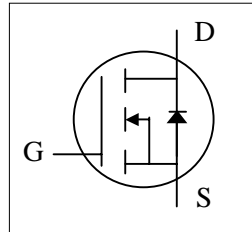




- ▼ Simple Drive Requirement
- ▼ Lower On-resistance
- ▼ Fast Switching Characteristic
- ▼ RoHS Compliant & Halogen-Free

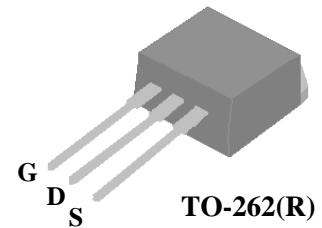


$BV_{DSS}$	60V
$R_{DS(ON)}$	3.5m $\Omega$
$I_D$	165A

### Description

Advanced Power MOSFETs from APEC provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-262 package is widely preferred for commercial-industrial power applications and suited for low voltage applications such as DC/DC converters.



### Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	60	V
$V_{GS}$	Gate-Source Voltage	+20	V
$I_D@T_C=25^\circ C$	Continuous Drain Current (Chip)	165	A
$I_D@T_C=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^3$	120	A
$I_D@T_C=100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	105	A
$I_{DM}$	Pulsed Drain Current <sup>1</sup>	300	A
$P_D@T_C=25^\circ C$	Total Power Dissipation	166	W
$P_D@T_A=25^\circ C$	Total Power Dissipation	2	W
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$

### Thermal Data

Symbol	Parameter	Value	Units
Rthj-c	Maximum Thermal Resistance, Junction-case	0.75	$^\circ C/W$
Rthj-a	Maximum Thermal Resistance, Junction-ambient	62	$^\circ C/W$



# AP9992GR-HF

## Electrical Characteristics @ $T_j=25^{\circ}\text{C}$ (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	60	-	-	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=10V, I_D=40A$	-	-	3.5	m $\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	2	-	5	V
$g_{fs}$	Forward Transconductance	$V_{DS}=10V, I_D=40A$	-	80	-	S
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=48V, V_{GS}=0V$	-	-	25	$\mu A$
$I_{GSS}$	Gate-Source Leakage	$V_{GS}=+20V, V_{DS}=0V$	-	-	$\pm 100$	nA
$Q_g$	Total Gate Charge	$I_D=40A$	-	135	216	nC
$Q_{gs}$	Gate-Source Charge	$V_{DS}=48V$	-	21	-	nC
$Q_{gd}$	Gate-Drain ("Miller") Charge	$V_{GS}=10V$	-	75	-	nC
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=30V$	-	28	-	ns
$t_r$	Rise Time	$I_D=40A$	-	115	-	ns
$t_{d(off)}$	Turn-off Delay Time	$R_G=3.3\Omega$	-	55	-	ns
$t_f$	Fall Time	$V_{GS}=10V$	-	100	-	ns
$C_{iss}$	Input Capacitance	$V_{GS}=0V$	-	5500	8800	pF
$C_{oss}$	Output Capacitance	$V_{DS}=25V$	-	930	-	pF
$C_{rss}$	Reverse Transfer Capacitance	$f=1.0\text{MHz}$	-	670	-	pF
$R_g$	Gate Resistance	$f=1.0\text{MHz}$	-	2	4	$\Omega$

## Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_{SD}$	Forward On Voltage <sup>2</sup>	$I_S=40A, V_{GS}=0V$	-	-	1.3	V
$t_{rr}$	Reverse Recovery Time	$I_S=10A, V_{GS}=0V,$	-	60	-	ns
$Q_{rr}$	Reverse Recovery Charge	$di/dt=100A/\mu s$	-	130	-	nC

### Notes:

1. Pulse width limited by Max. junction temperature.
2. Pulse test
3. Package limitation current is 120A.

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

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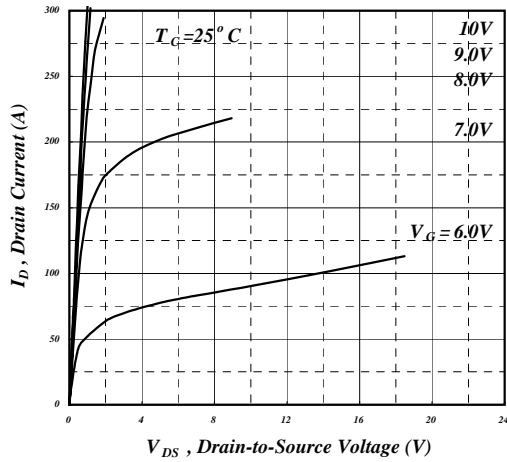


Fig 1. Typical Output Characteristics

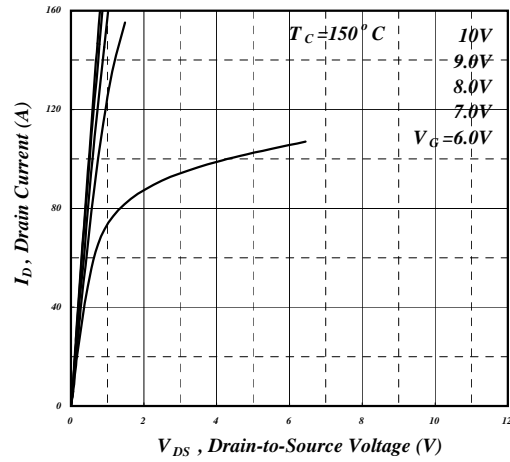


Fig 2. Typical Output Characteristics

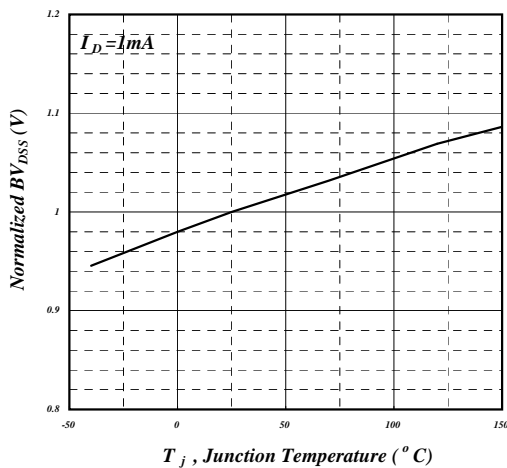


Fig 3. Normalized  $BV_{DSS}$  v.s. Junction Temperature

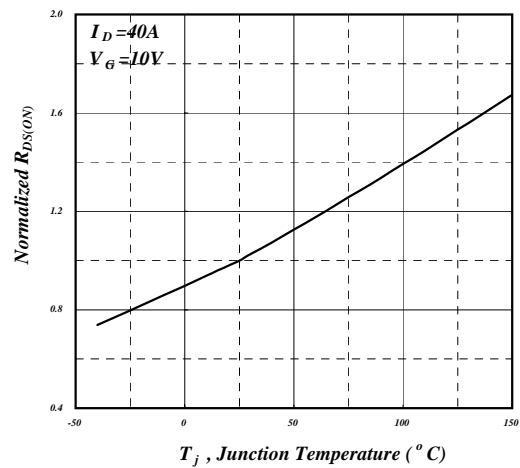


Fig 4. Normalized On-Resistance v.s. Junction Temperature

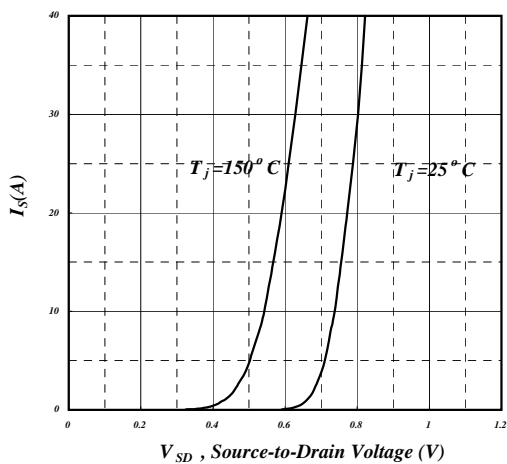


Fig 5. Forward Characteristic of Reverse Diode

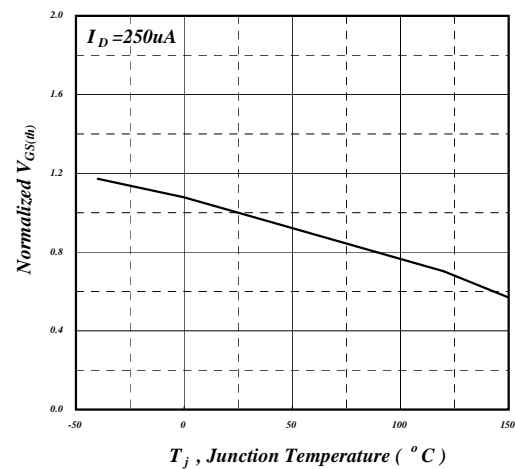


Fig 6. Gate Threshold Voltage v.s. Junction Temperature

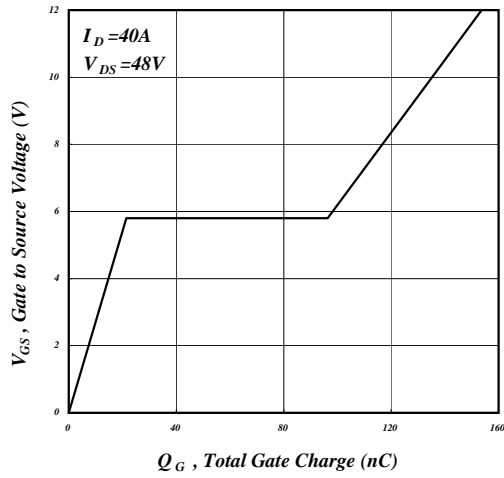


Fig 7. Gate Charge Characteristics

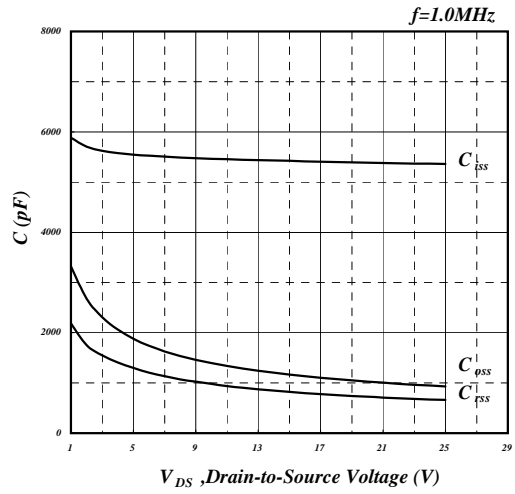


Fig 8. Typical Capacitance Characteristics

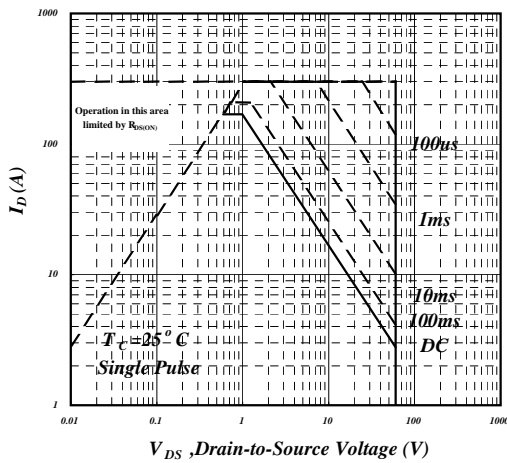


Fig 9. Maximum Safe Operating Area

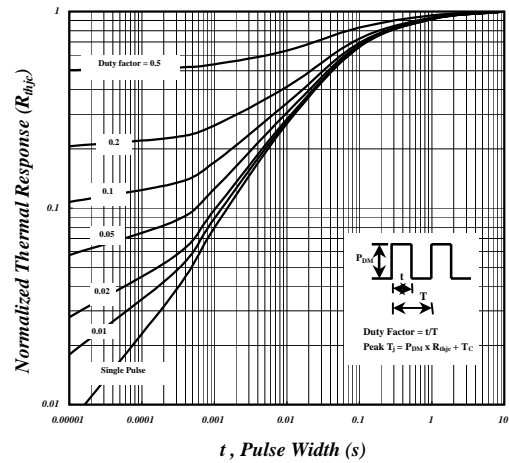


Fig 10. Effective Transient Thermal Impedance

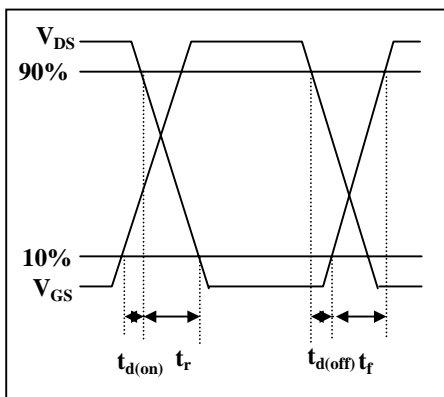


Fig 11. Switching Time Waveform

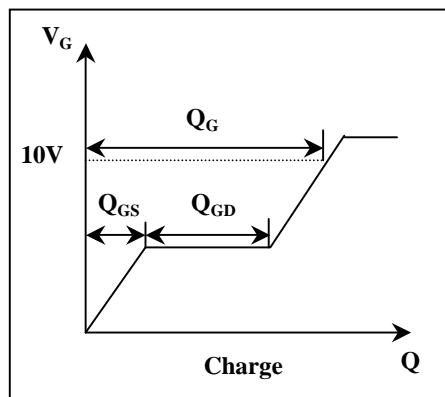


Fig 12. Gate Charge Waveform